

## VieTape TIM4104

### HIGH THERMALLY CONDUCTIVE GAP FILLER PAD

#### DESCRIPTION

High thermal conductive gap filler pad that has low thermal resistance and excellent electrical insulation at low compression. It can work stably at -60°C-200°C

#### APPLICATIONS

Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, ...

#### TYPICAL PERFORMANCE PROPERTIES

PROPERTIES	VALUE	METHOD
Appearance	Purple	Visual
Thickness	0.5-10.0 mm	ASTM D374
Density	3.1 g/cm <sup>3</sup>	ASTM D792
Working Temperature	-60 to 200°C	-
Hardness	50-60 shore 00	ASTM D2240
ELECTRICAL PROPERTIES		
Breakdown Voltage	>6.0 kV/mm	ASTM D149
Volume Resistivity	10 <sup>13</sup> Ohm-cm	ASTM D257
Dielectric Constant@1MHz	7.0	ASTM D150
THERMAL PROPERTIES		
Thermal conductivity	4.0 W/m.K	ISO22007-2
Flammability	Meet UL94-V0	

#### SHELF LIFE AND STORAGE

12 months from date of manufacture when stored at 10 - 30°C and 40 - 50% relative humidity. Avoid extrusion and exposure to the sun.

#### CAUTION

For safe handling information on this product, please review the Safety Data Sheet, SDS

The data contained in this bulletin is provided only as a guide for evaluation/consideration. These material characteristics are typical properties that are based on a limited number of samples tested in the laboratory. We cannot assume responsibility for results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any product or method. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide.

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